

Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from, Europe, America and south Asia, supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts, Customers Priority, Honest Operation, and Considerate Service", our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip, ALPS, ROHM, Xilinx, Pulse, ON, Everlight and Freescale. Main products comprise IC, Modules, Potentiometer, IC Socket, Relay, Connector. Our parts cover such applications as commercial, industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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Slotted Optical Switch

OPB660N, OPB660T



Features:

- Non-contact switching
- Printed circuit board mounting
- Enhanced signal to noise ratio
- Gap 0.125" (3.18mm) wide and 0.345" (8.76mm) deep slot
- Emitter Aperture 0.05" X 0.06" (1.27mm X 1.52mm),
- Sensor Aperture 0.01" X 0.06" (0.25mm X 1.52mm)





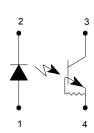
Description:

Each OPB660 slotted optical switch consists of an infrared emitting diode and a NPN silicon phototransistor, combined with an enhanced low current roll-off that improves contrast ratio and provides immunity to background irradiance. Housings are made from an opaque grade of injection-molded plastic to minimize sensitivity to both visible and near-infrared light.

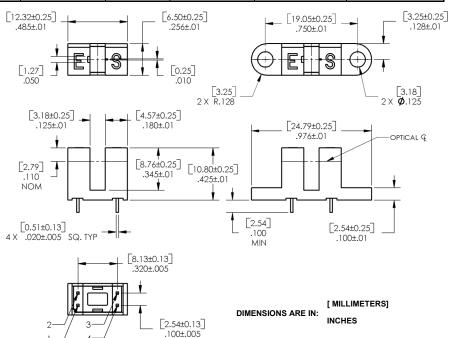
Applications:

- Non-contact transmissive object sensor
- Assembly line automation
- Machine automation
- Machine safety
- End of travel sensor
- Door sensor

Part Number	LED Peak Wavelength	Sensor	Slot Width / Depth	Aperture Emitter/Sensor	Lead Length / Spacing
OPB660N	890 nm	Rbe Transistor	0.125" / 0.345"	0.05" / 0.01"	0.100" / 0.320"
OPB660T	030 11111			0.03 / 0.01	(MIN)



Pin#	LED	Pin#	Transistor
1	Anode	3	Collector
2	Cathode	4	Emitter





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Power Dissipation⁽³⁾



Electrical Specifications

Absolute Maximum Ratings (T_A=25°C unless otherwise noted)

Storage & Operating Temperature Range	-40° C to +100° C
Lead Soldering Temperature [1/16 inch (1.6mm) from the case for 5 sec. with soldering iron] ⁽¹⁾	260°C
Input Diode	
Forward DC Current	50 mA
Peak Forward Current (1 μs pulse width, 300 pps)	1 A
Reverse DC Voltage	3 V
Power Dissipation ⁽²⁾	100 mW
Output Phototransistor	
Collector-Emitter Voltage	24 V
Collector DC Current	30 mA

Electrical Characteristics (T_A = 25°C unless otherwise noted)

SYMBOL	PARAMETER	MIN	TYP	MAX	UNITS	TEST CONDITIONS	
Input Diode							
V_{F}	Forward Voltage	-	ı	1.6	V	I _F = 10 mA	
I_R	Reverse Current	-	1	100	μΑ	V _R = 3 V	
Output Phototransistor							
V _{(BR)CEO}	Collector-Emitter Breakdown Voltage	24	- 1	-1	V	Ι _{CE} = 100 μΑ	
BV_{ECO}	Emitter Reverse Breakdown Voltage	0.4	ı	1	٧	I _{EC} = 100 μA	
I _{CEO}	Collector-Emitter Dark Current	-	ı	100	μΑ	V _{CE} = 5 V	
Combined							
V_{SAT}	Collector-Emitter Saturation Voltage	-	-	0.4	V	$I_F = 10$ mA, $I_C = 100$ μ A, (gap unblocked)	
I _{C(ON)}	On-State Collector Current	600	-	-	μΑ	I _F = 10 mA, V _{CE} = 5 V	

Notes:

- (1) RMA flux is recommended. Duration can be extended to 10 seconds maximum when flow soldering. A maximum of 20 grams force may be applied to leads when soldering.
- (2) Derate linearly 1.33 mW/° C above 25° C.
- (3) Derate linearly 2.0 mW/° C above 25° C.

200 mW

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Performance

